

# SN54LS11, SN54S11, SN74LS11, SN74S11 TRIPLE 3-INPUT POSITIVE-AND GATES

SDLS131 – APRIL 1985 – REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

## description

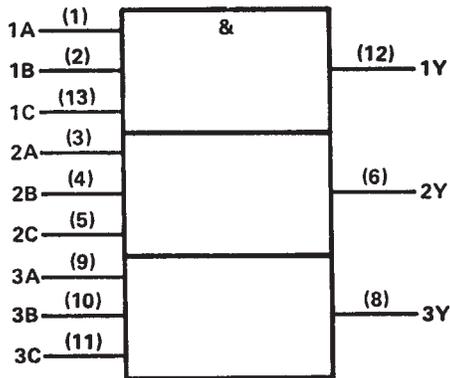
These devices contain three independent 3-input AND gates.

The SN54LS11 and SN54S11 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74LS11 and SN74S11 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE (each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	H
L	X	X	L
X	L	X	L
X	X	L	L

## logic symbol†

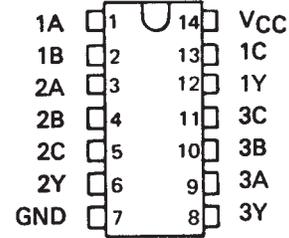


†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

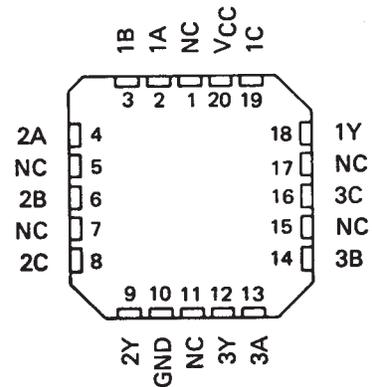
## SN54LS11, SN74S11 . . . J OR W PACKAGE SN74LS11, SN74S11 . . . D OR N PACKAGE

(TOP VIEW)



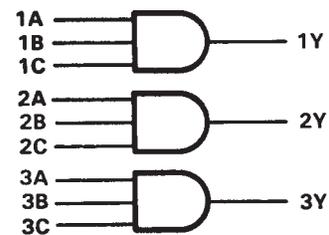
## SN54LS11, SN54S11 . . . FK PACKAGE

(TOP VIEW)



NC—No internal connection

## logic diagram (positive logic)



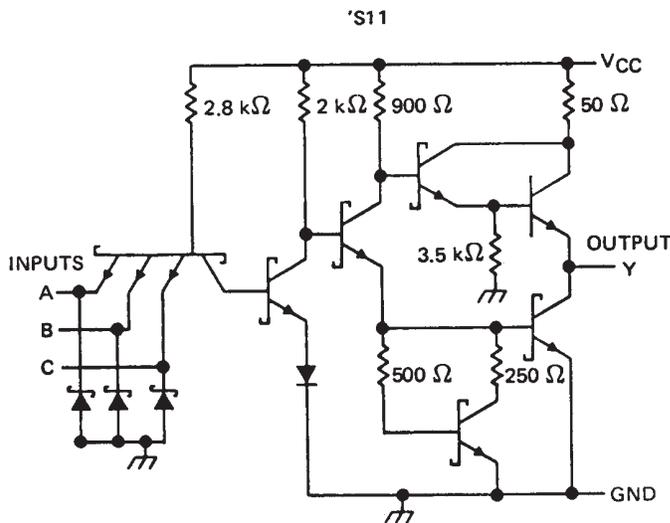
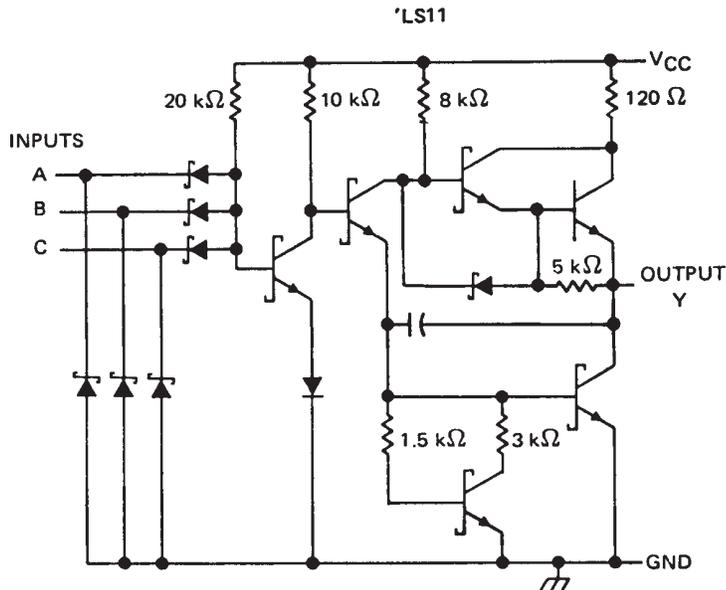
$$Y = A \cdot B \cdot C \text{ or}$$

$$Y = \overline{\overline{A} + \overline{B} + \overline{C}}$$

**SN54LS11, SN54S11,  
SN74LS11, SN74S11  
TRIPLE 3-INPUT POSITIVE-AND GATES**

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**schematics (each gate)**



Resistor values shown are nominal.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)**

Supply voltage, $V_{CC}$ (see Note 1) .....	7 V
Input voltage: 'S11 .....	5.5 V
'LS11 .....	7 V
Operating free-air temperature range: SN54' .....	-55°C to 125°C
SN74' .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



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**recommended operating conditions**

	SN54LS11			SN74LS11			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage	0.7			0.8			V
I <sub>OH</sub> High-level output current	- 0.4			- 0.4			mA
I <sub>OL</sub> Low-level output current	4			8			mA
T <sub>A</sub> Operating free-air temperature	- 55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS †	SN54LS11		SN74LS11		UNIT
		MIN	TYP ‡	MAX	MIN	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = - 18 mA			- 1.5		V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OH</sub> = - 0.4 mA	2.5	3.4	2.7	3.4	V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 4 mA	0.25	0.4	0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, I <sub>OL</sub> = 8 mA			0.35	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V	0.1		0.1		mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V	20		20		μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V	- 0.4		- 0.4		mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	- 20	- 100	- 20	- 100	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V	1.8	3.6	1.8	3.6	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V	3.3	6.6	3.3	6.6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A, B or C	Y	R <sub>L</sub> = 2 kΩ,	C <sub>L</sub> = 15 pF		8	15	ns
t <sub>PHL</sub>						10	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

**SN54LS11, SN54S11,  
SN74LS11, SN74S11  
TRIPLE 3-INPUT POSITIVE-AND GATES**

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**recommended operating conditions**

	SN54S11			SN74S11			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			0.8	V
I <sub>OH</sub> High-level output current			-1			-1	mA
I <sub>OL</sub> Low-level output current			20			20	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS †	SN54S11			SN74S11			UNIT
		MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.2			-1.2	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -1 mA	2.5	3.4		2.7	3.4		V
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA			0.5			0.5	V
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V			1			1	mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			50			50	µA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V			-2			-2	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX	-40		-100	-40		-100	mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		13.5	24		13.5	24	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V		24	42		24	42	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A, B or C	Y	R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 15 pF		4.5	7	ns
t <sub>PHL</sub>					5	7.5	ns
t <sub>PLH</sub>			R <sub>L</sub> = 280 Ω, C <sub>L</sub> = 50 pF		6		ns
t <sub>PHL</sub>					7.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
JM38510/08001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/08001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
JM38510/31001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/31001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/31001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/08001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/08001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/31001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/31001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/31001BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SN54LS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54S11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74LS11D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS11N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS11N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS11NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS11NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS11NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74LS11NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S11D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	
SN74S11N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74S11N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SNJ54LS11FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS11W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S11FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S11J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S11W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN54LS11, SN54S11, SN74LS11, SN74S11 :**

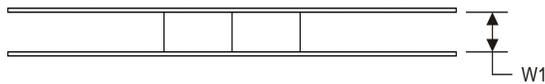
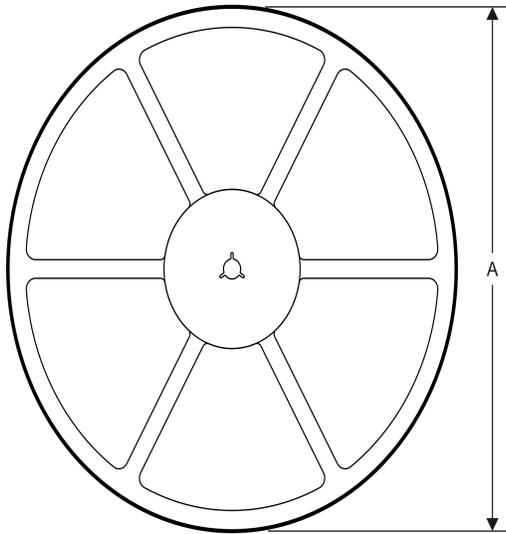
- Catalog: [SN74LS11](#), [SN74S11](#)
- Military: [SN54LS11](#), [SN54S11](#)

NOTE: Qualified Version Definitions:

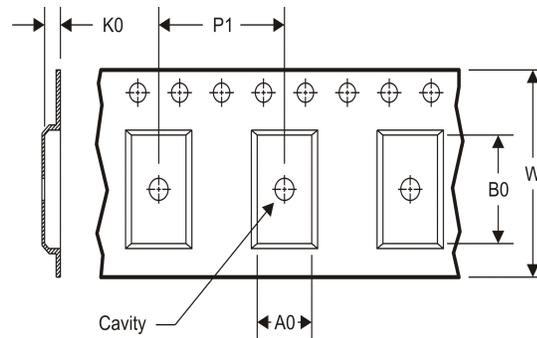
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS11DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS11NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

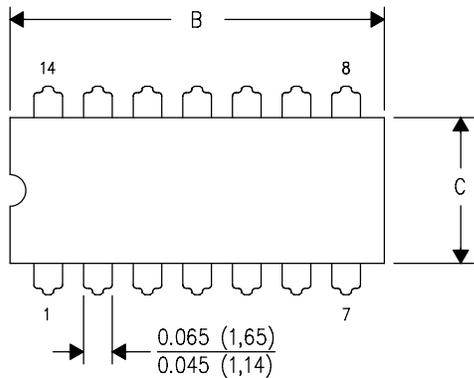

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS11DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS11NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

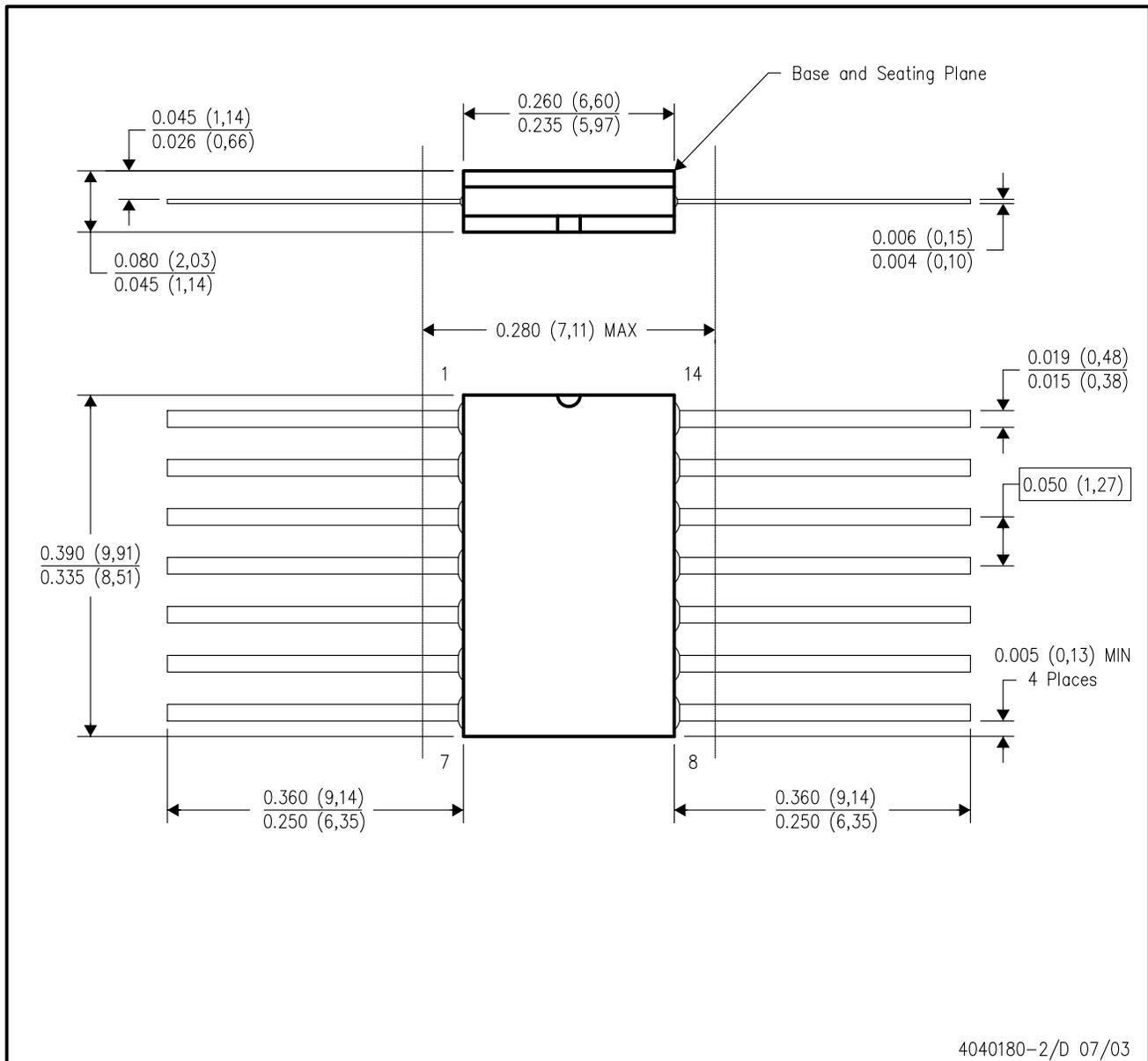


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- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

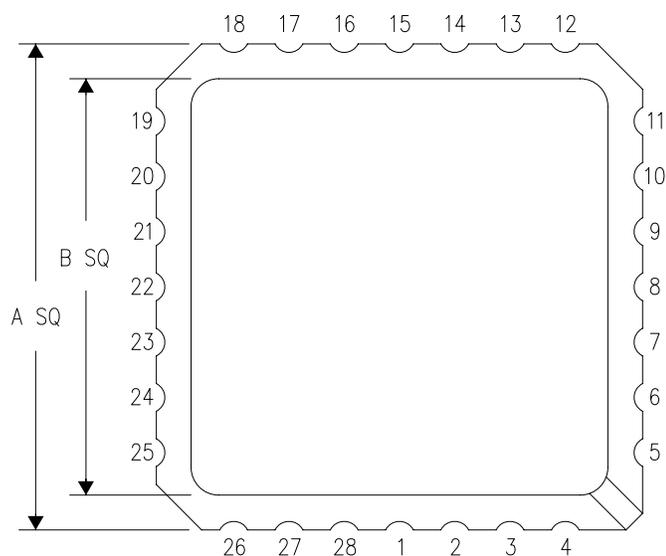


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

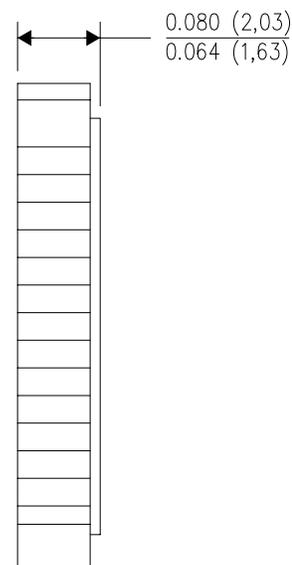
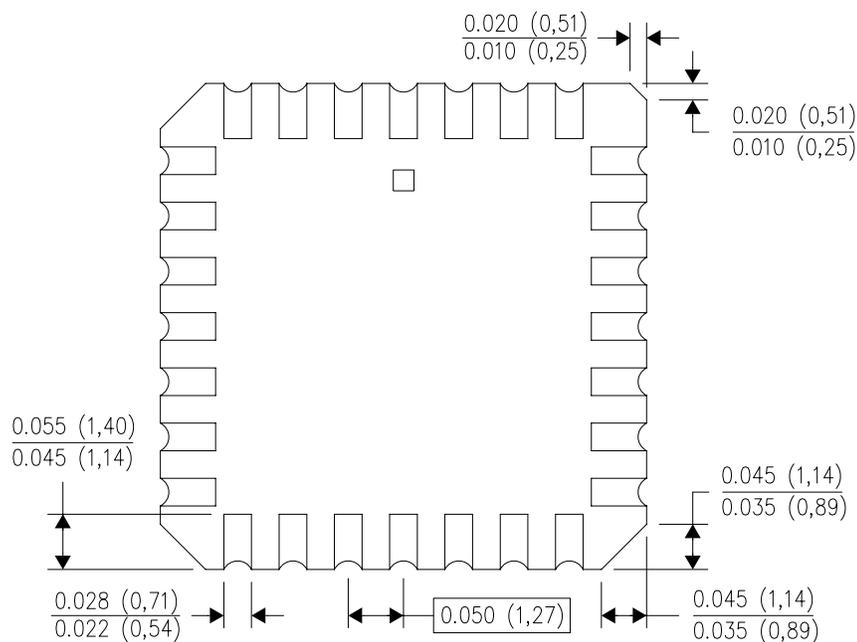
FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



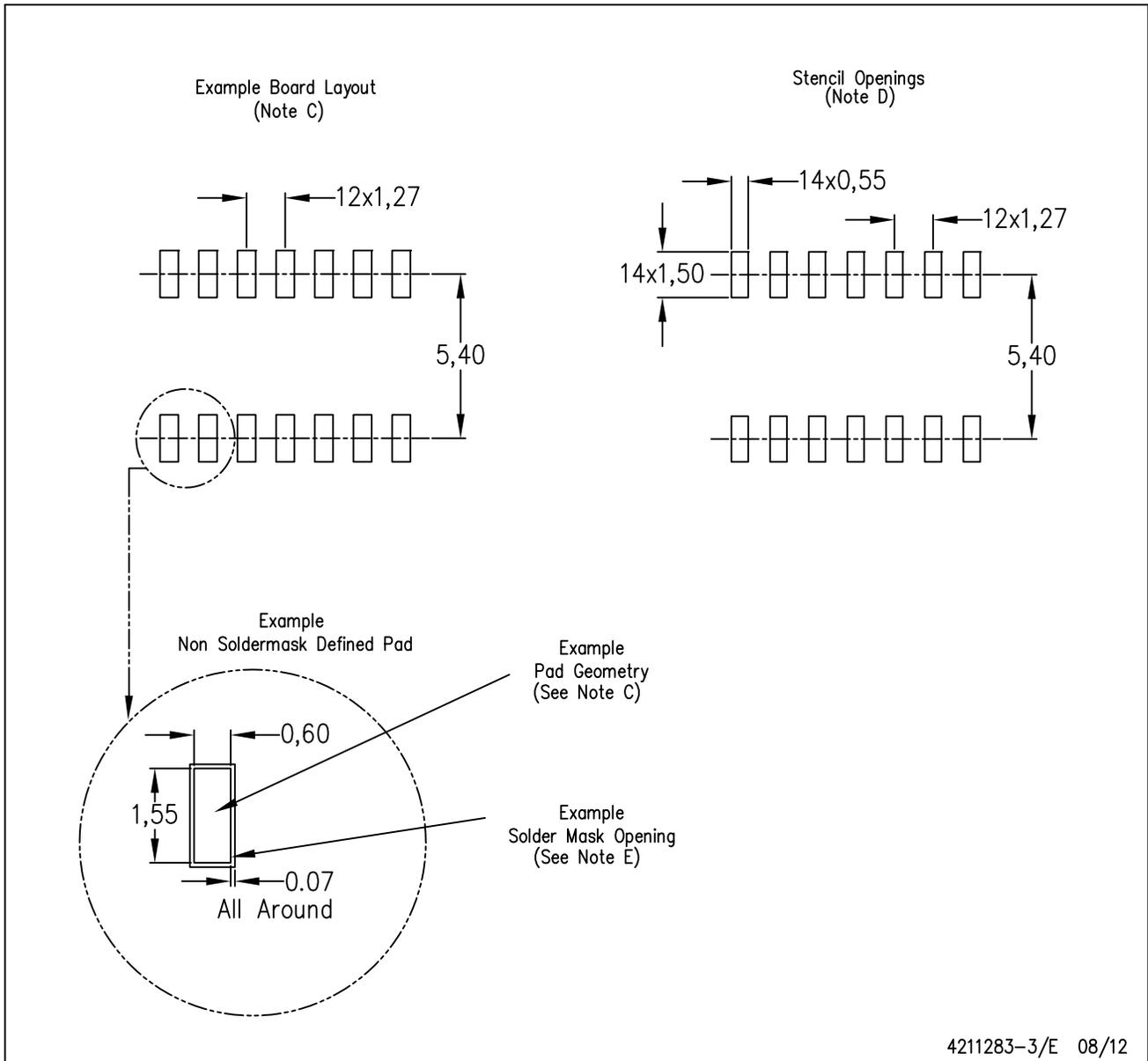
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

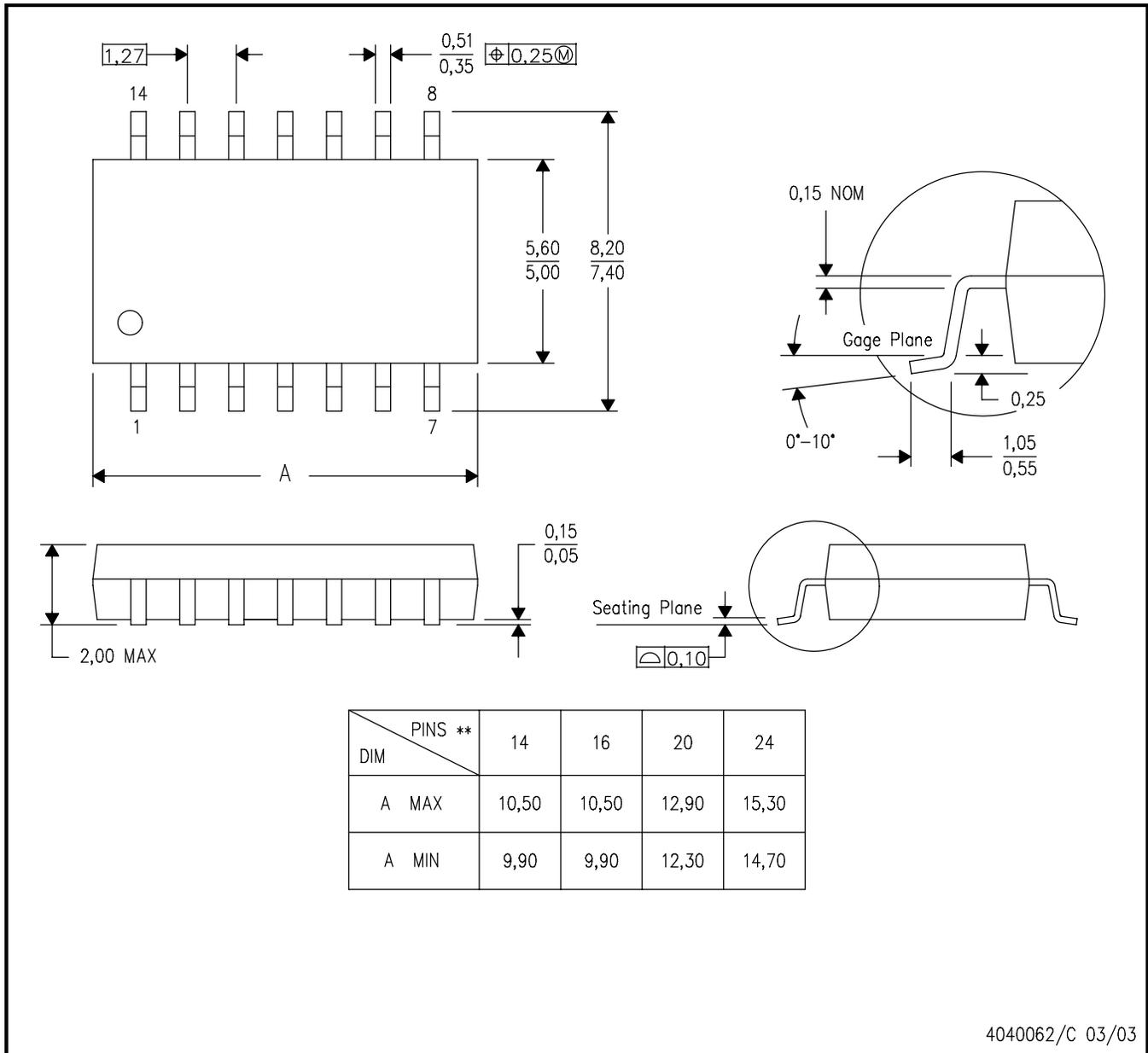
- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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